# METHOD OF FORMING SOLDER BUMPS ON AN INTEGRATED CIRCUIT FLIP CHIP

Abstract:

A method of forming solder bumps (56) for use as terminals of an integrated circuit flip chip encompasses the use of a photoresist (52) which can be selectively patterned (54) with known photoengraving techniques, through which a preformulated solder composition can be accurately and selectively deposited on the surface (50) of the flip chip. A dry film photoresist (52) is used as a mask to apply a solder paste (56), such that precise registration, fine pitch bump arrays, and precise bump size control are possible. Precise control of the composition of the solder bumps (58) is also enabled, which relies on processing techniques which minimise processing costs. The process does not generate chlorofluorocarbons.